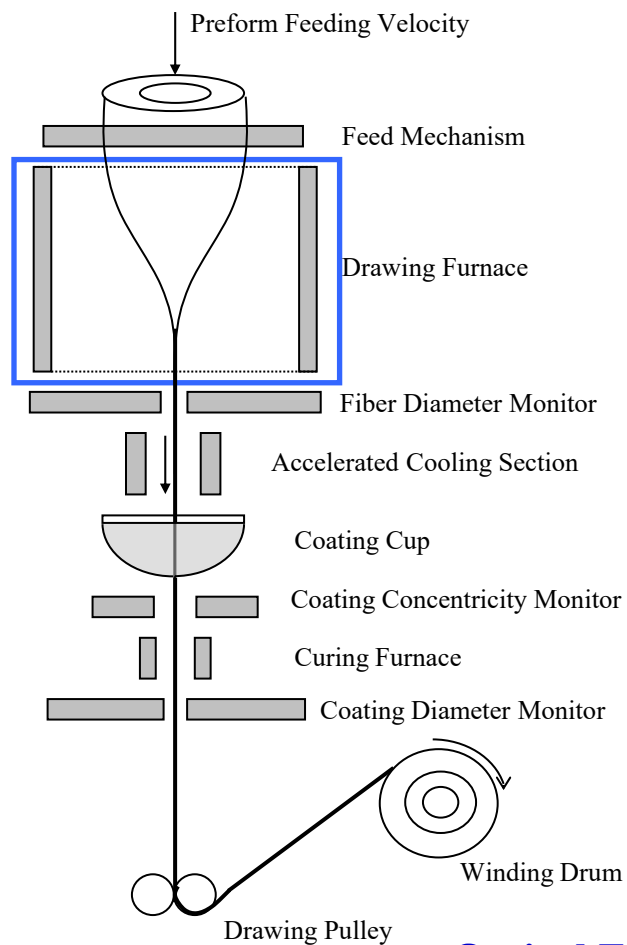
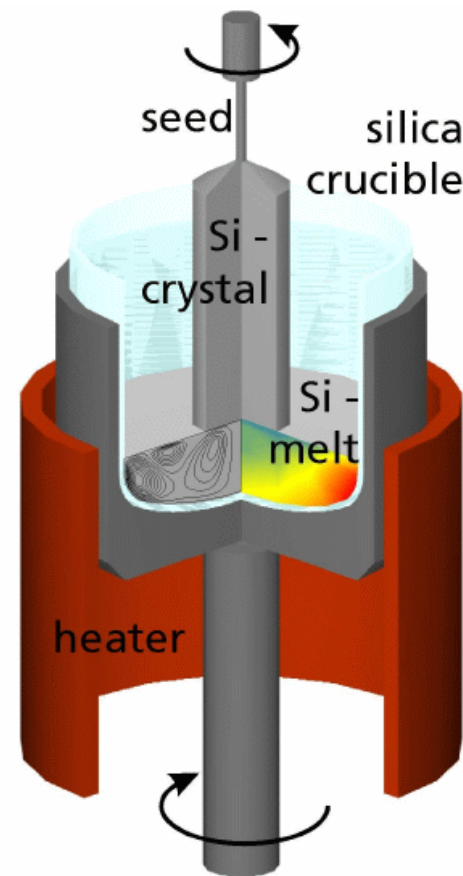


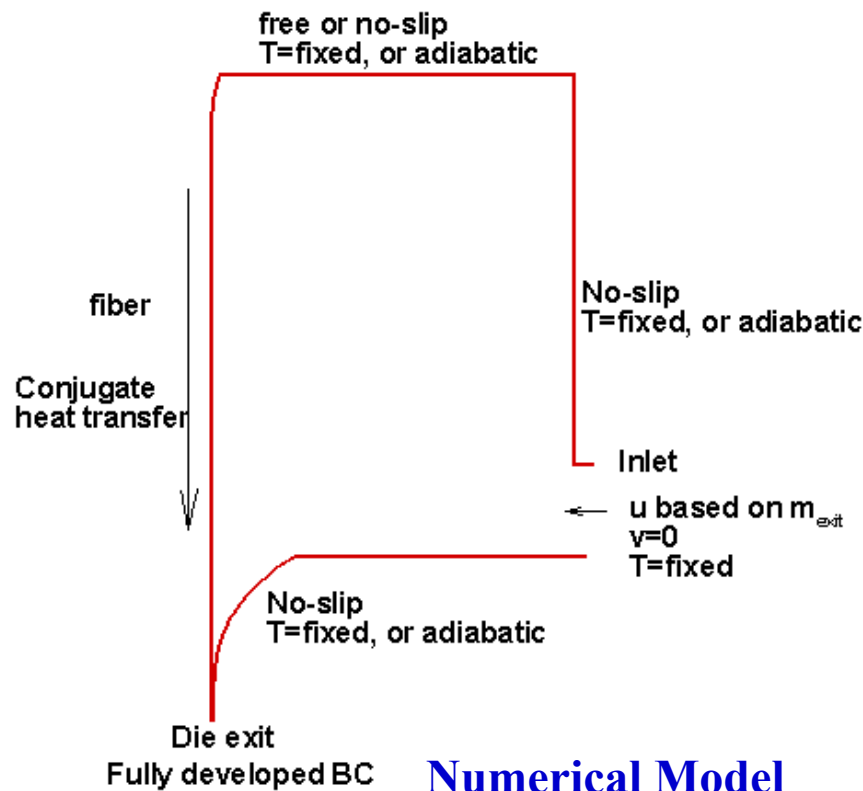
Optical Fiber Drawing and Czochralski Crystal Growing



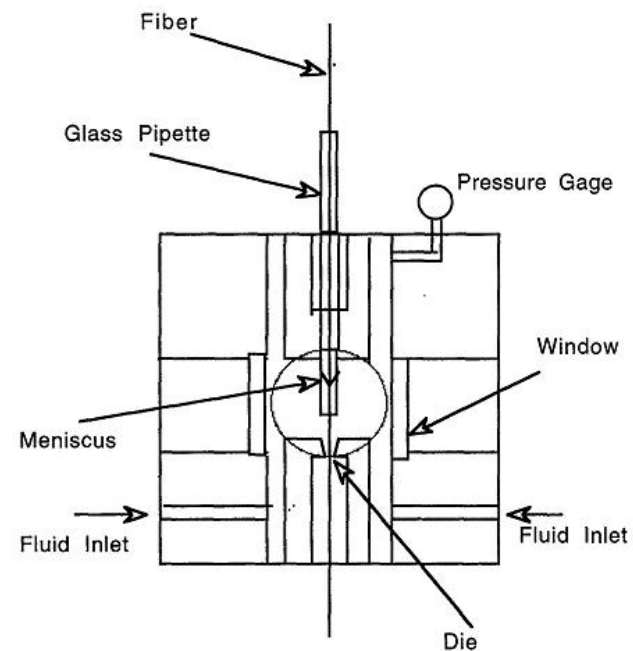
Optical Fiber Drawing



An Optical Fiber Coating Applicator

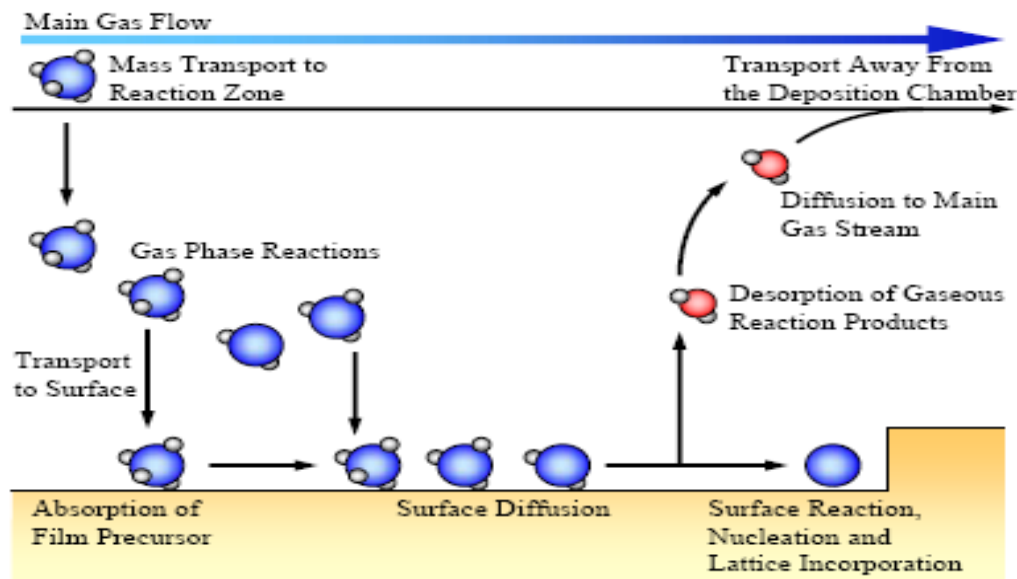


Numerical Model

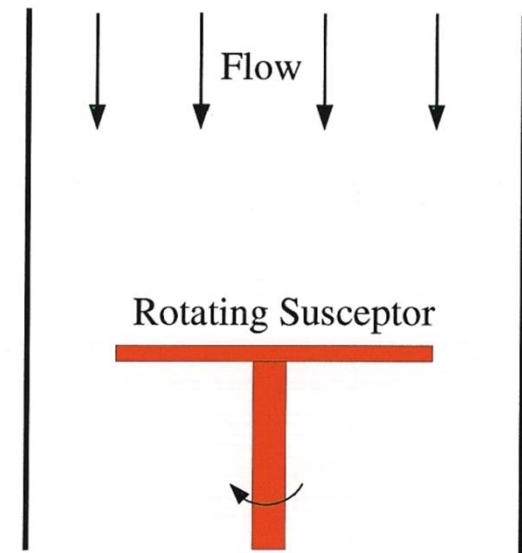


Experimental System

Chemical Vapor Deposition

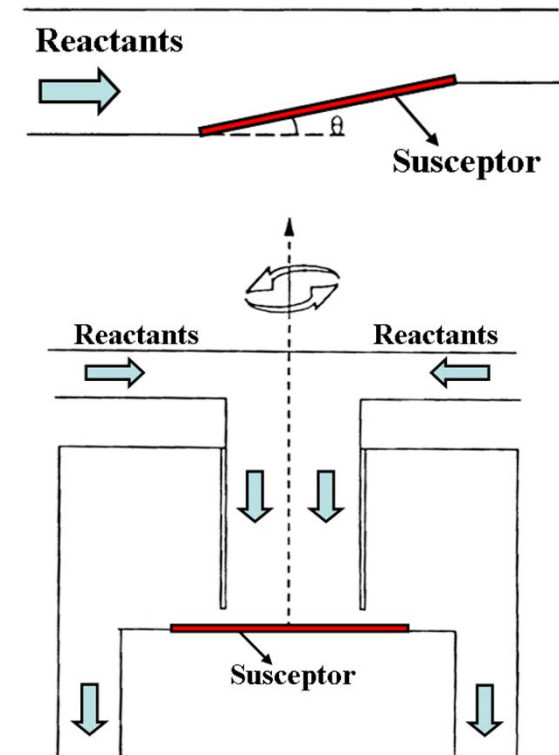
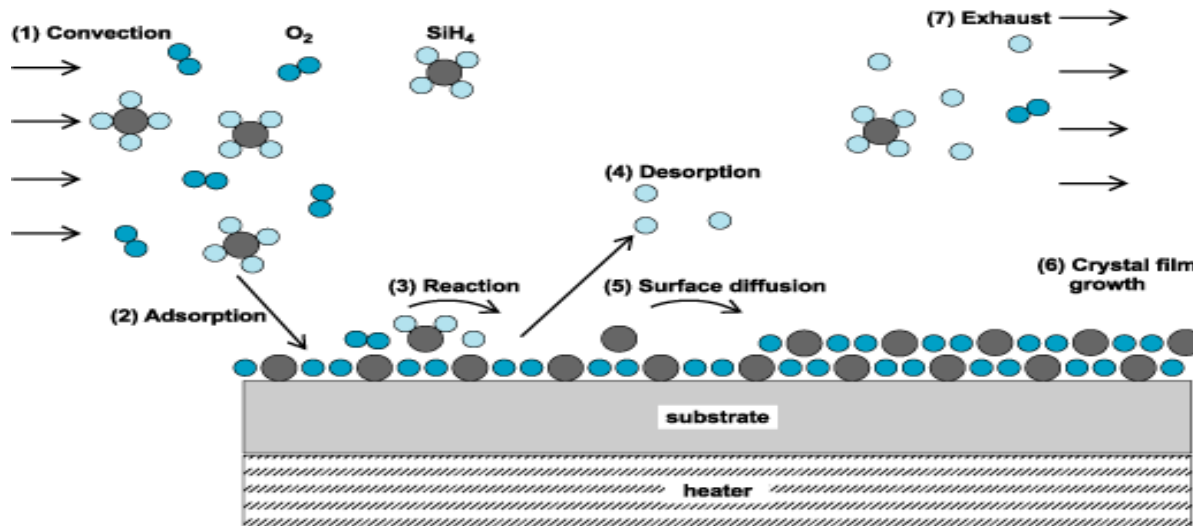


• Vertical Reactor



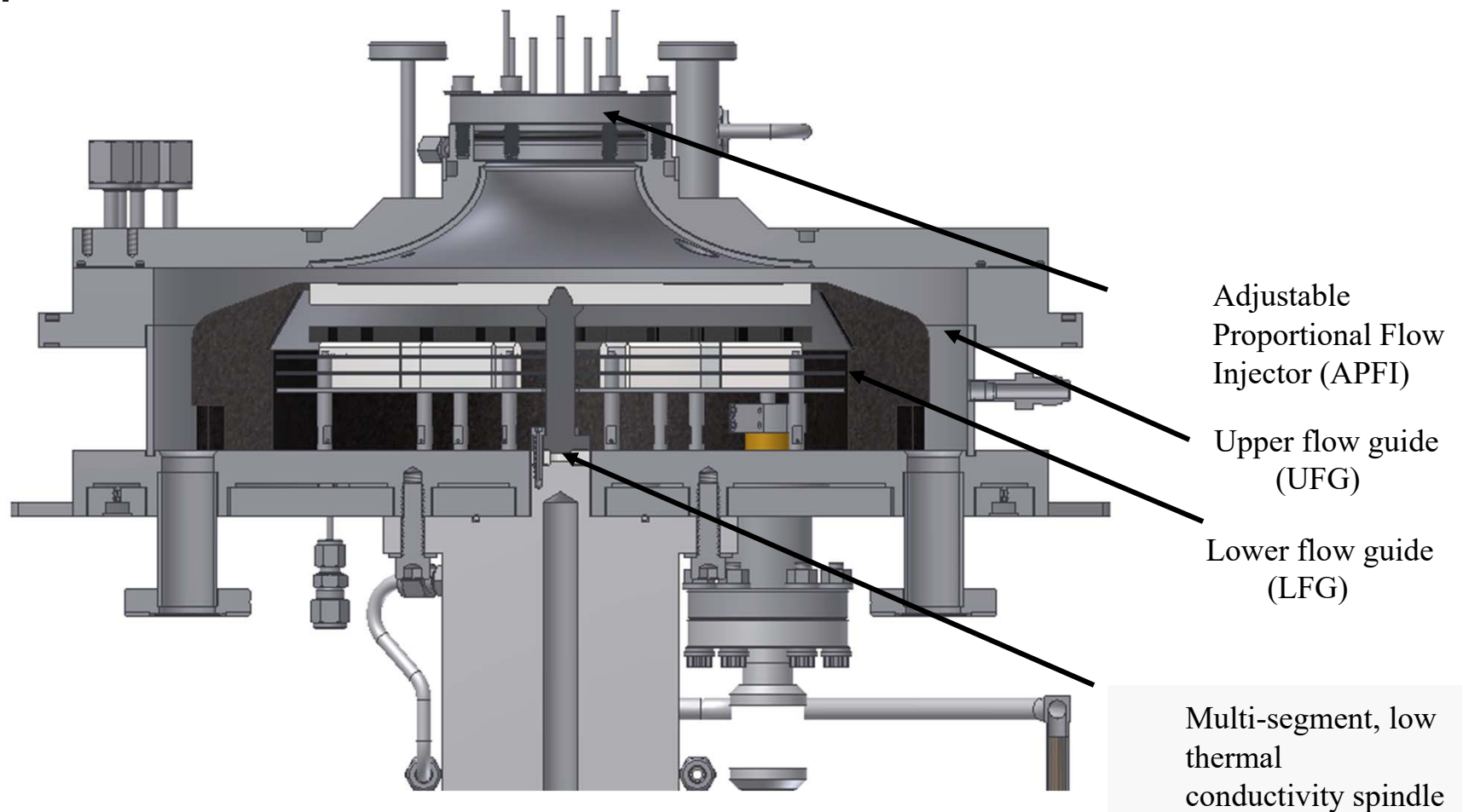
- **Chemical Transformations and Deposition at Micro/Nanoscale**
- **Boundary Conditions and System at Macro/Engineering Scale**
- **Desire High Deposition Rates, with Uniform, High Quality, Film**
- **Minimum Loss of Reacting Gases**

Chemical Vapor Deposition

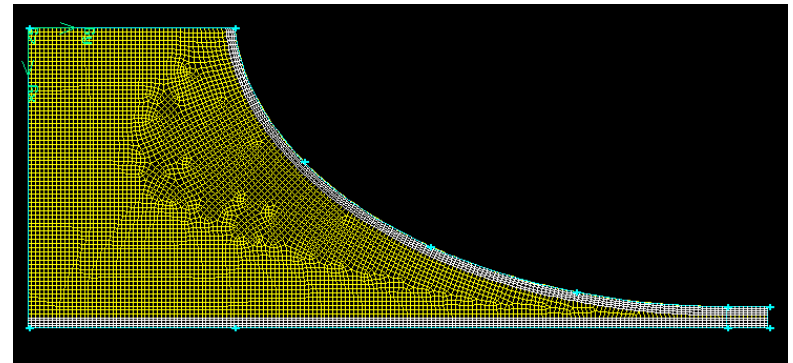
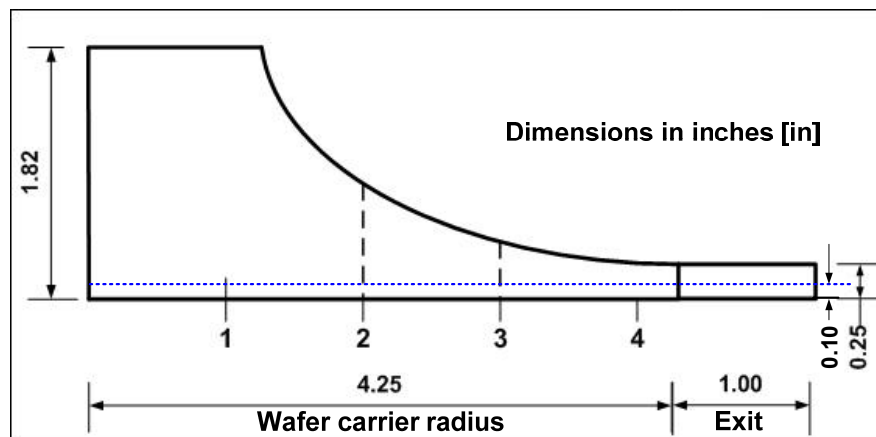


Desire High Deposition Rates, with Uniform, High Quality, Film

Industrial CVD Reactor for Gallium Nitride (GaN)

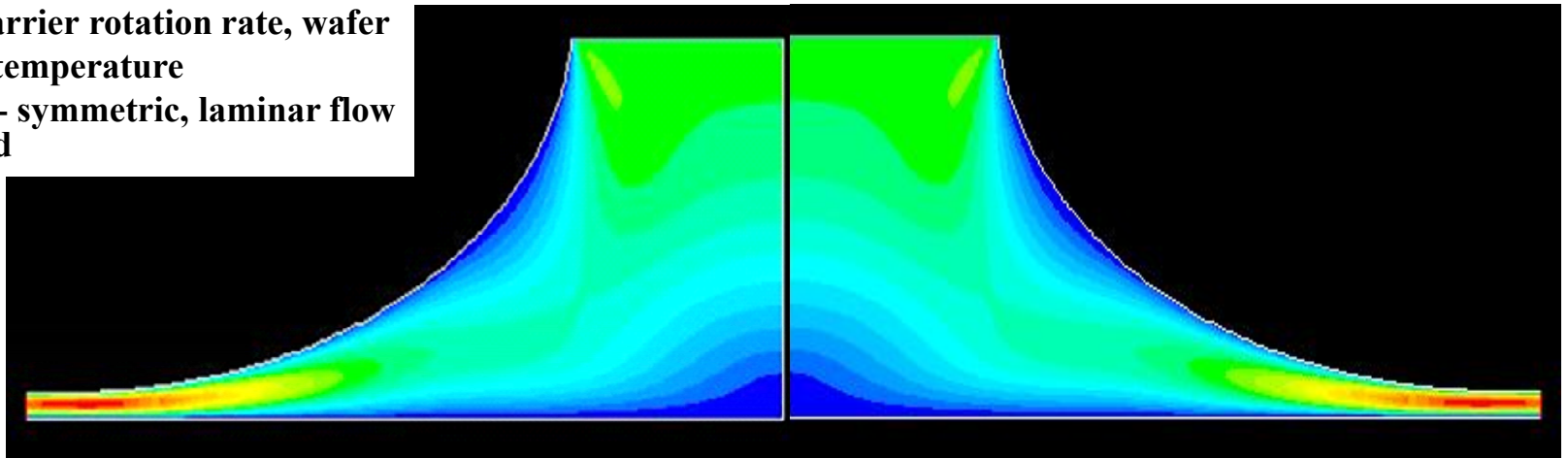


Analysis of Flow Field

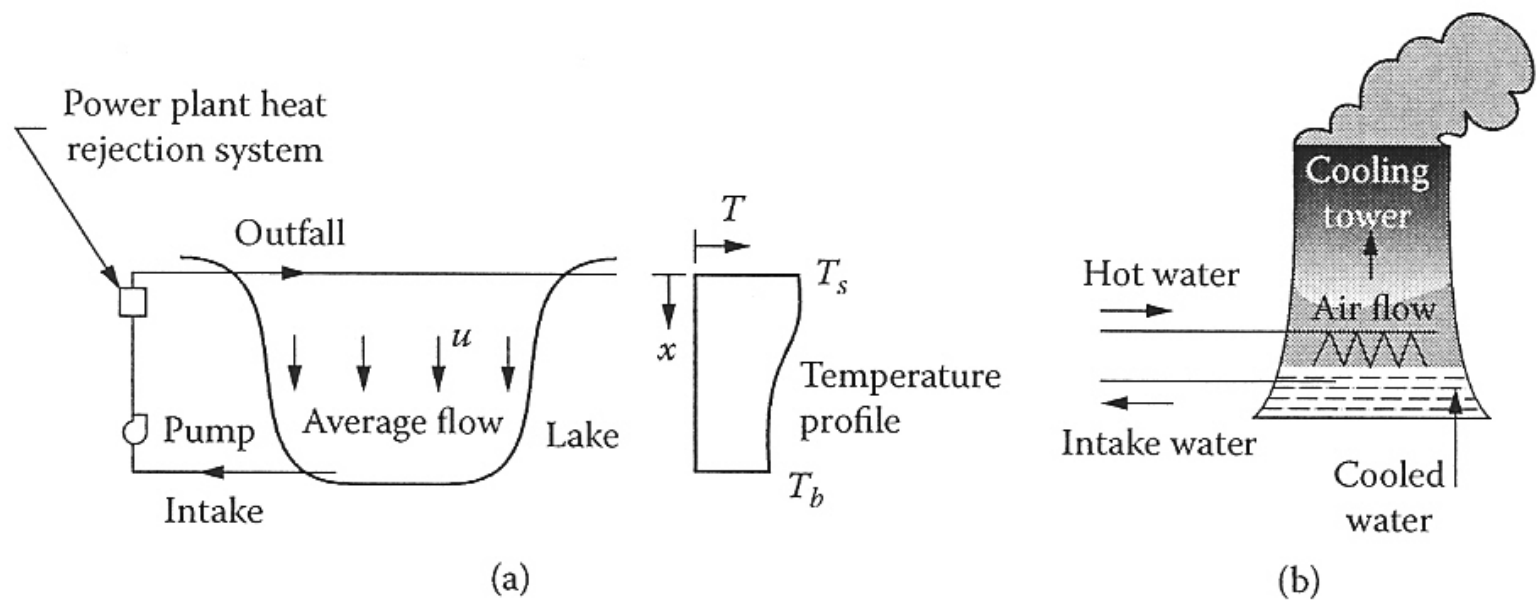


**Factors – gas flow rate, pressure,
wafer carrier rotation rate, wafer
carrier temperature**

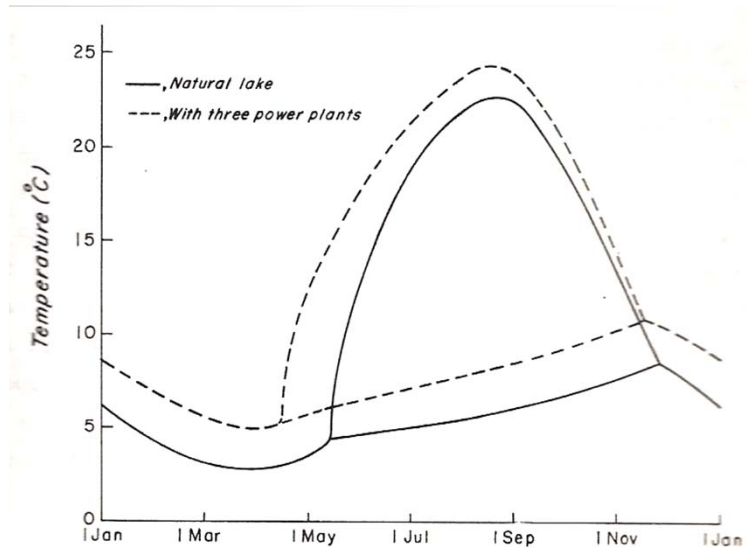
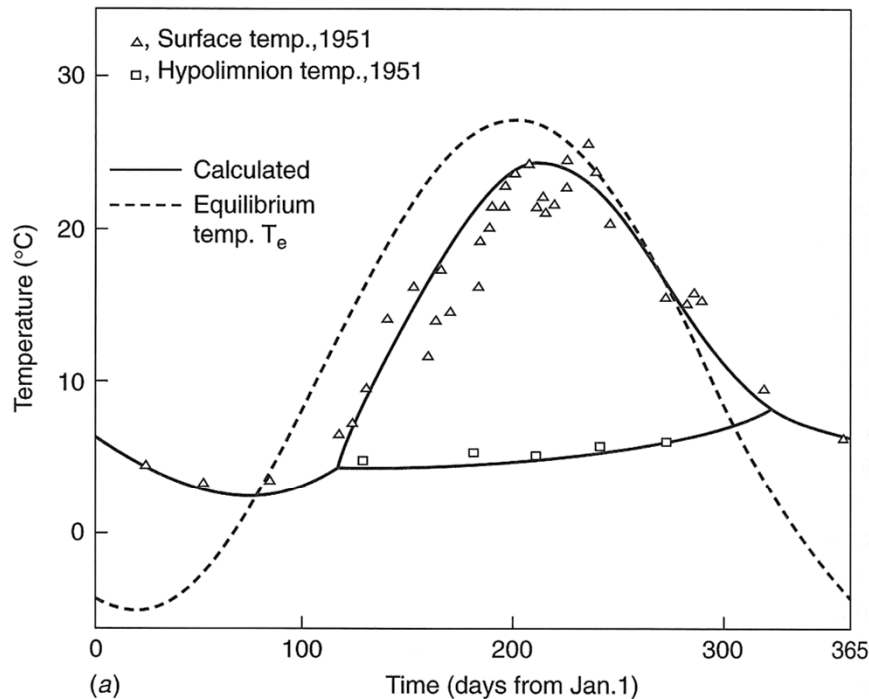
**Results - symmetric, laminar flow
field**



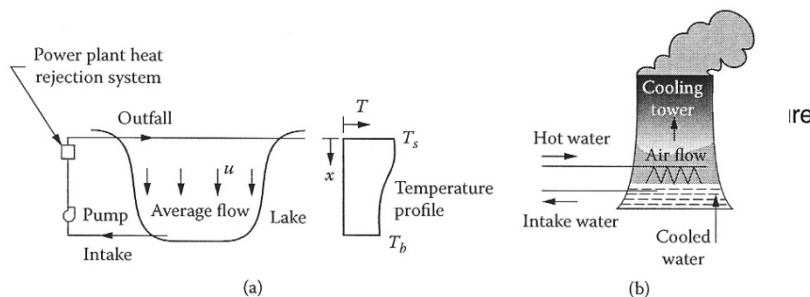
Heat Rejection from a Power Plant to a Lake and a Cooling Tower



Environmental Effect of Thermal Discharge to a Water Body

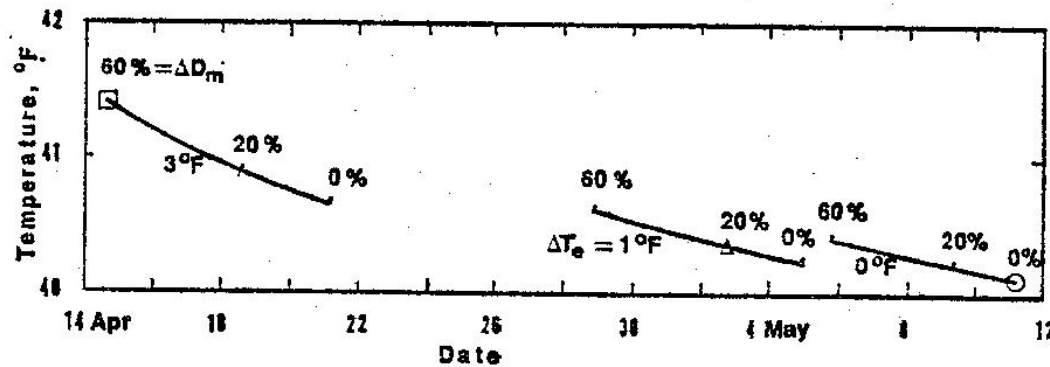


$$\int_0^{365} q''_{\text{surface}} dt = Q_{\text{rejected}}$$

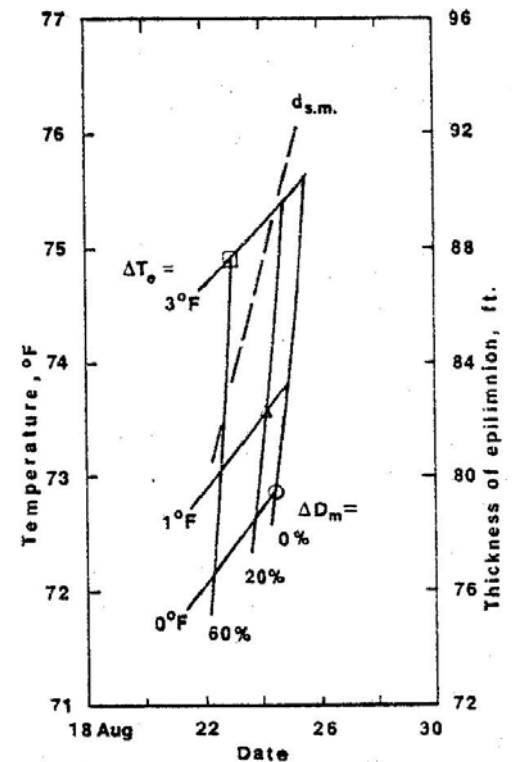


Relatively small temperature changes
Effect on natural cycle
Effect on transport processes
Effect on bio-organisms

Effects of Heat Rejection from a Power Plant to a Lake

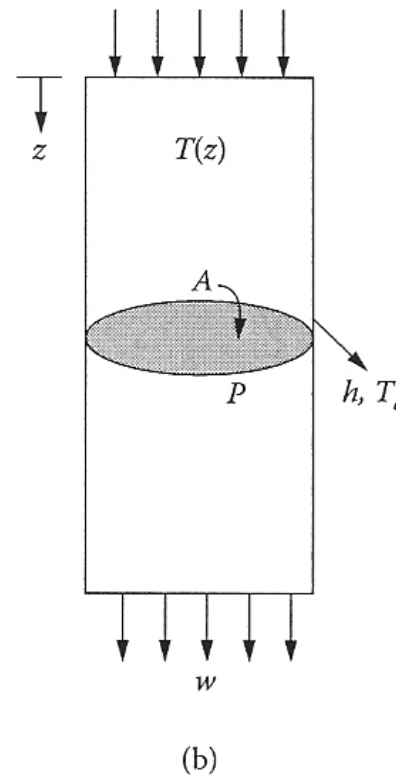
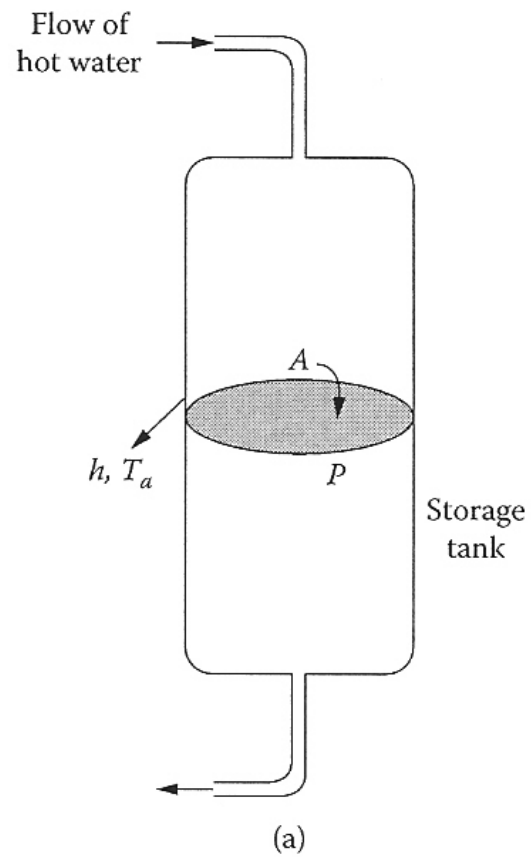


Onset of stratification

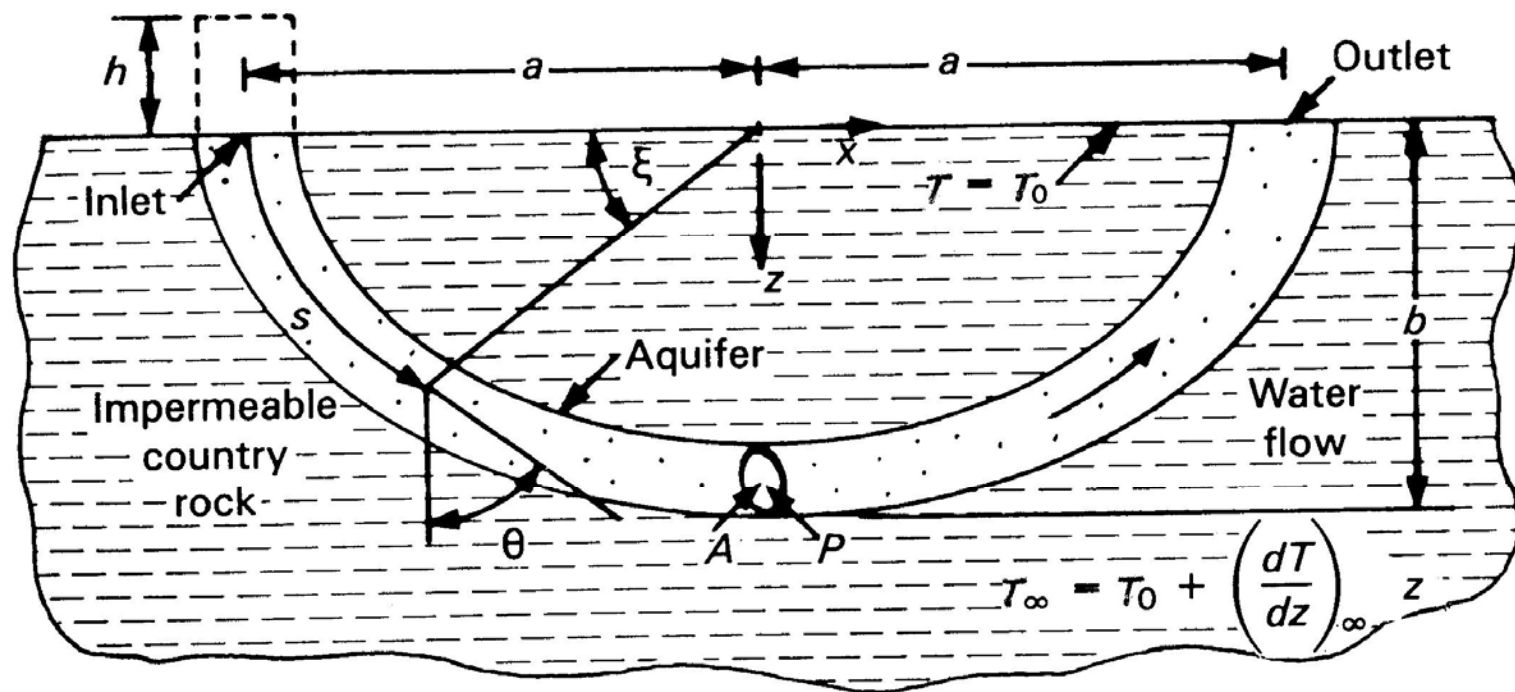


Summer maximum
and epilimnion depth

Energy Storage as Sensible Heat

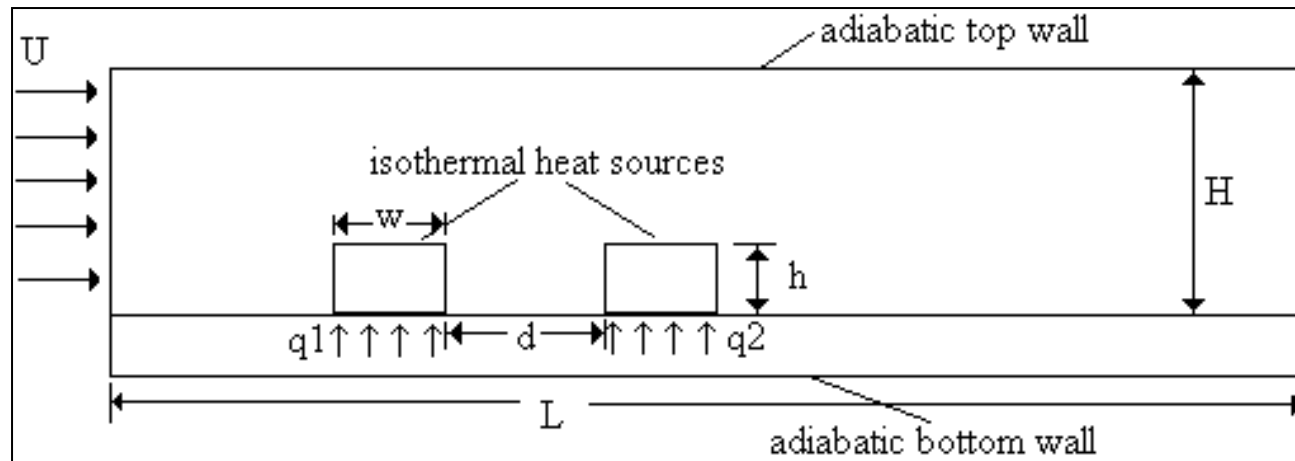


Schematic of an Open-Loop Thermosyphon (the Aquifer)



From Torrance (1979)

Numerical Modeling of Air Cooled Electronic System

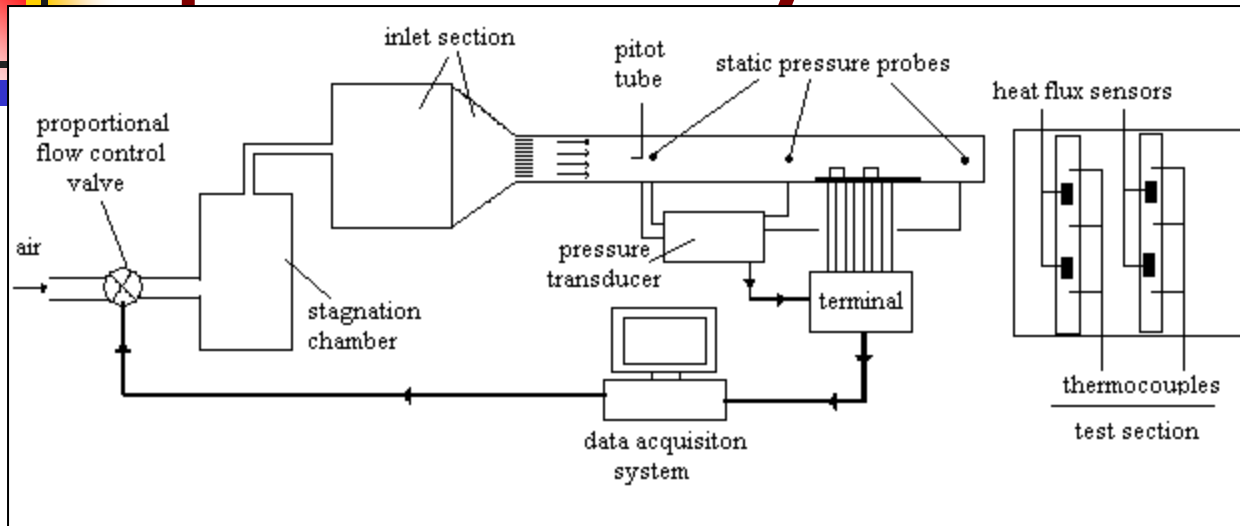


$$\nabla \cdot \vec{V} = 0$$

$$\frac{\partial \vec{V}}{\partial \tau} + \vec{V} \cdot \nabla \vec{V} = -\nabla P + \frac{1}{Re} \nabla^2 \vec{V} - \frac{Gr}{Re^2} \theta \vec{g}$$

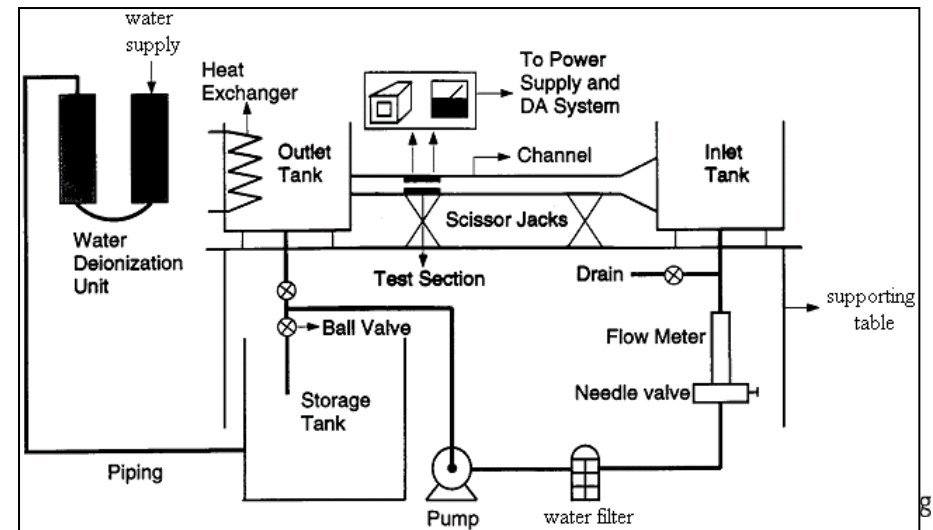
$$\frac{\partial \theta}{\partial \tau} + \vec{V} \cdot \nabla \theta = \frac{1}{RePr} \nabla^2 \theta$$

Experimental Systems



Air Cooling System

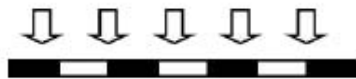
Liquid Cooling System



Microchannel Heat Sinks: Different Scales in Different Components



(a) N type Si (100)



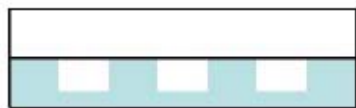
(b) Photolithography



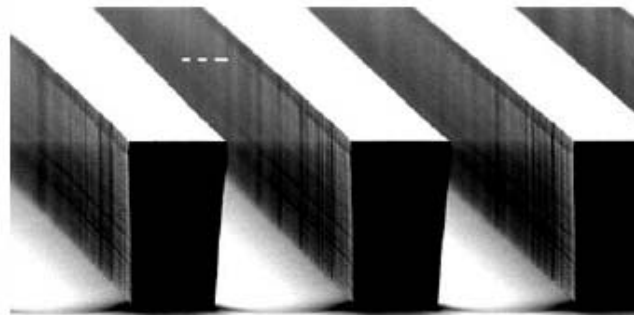
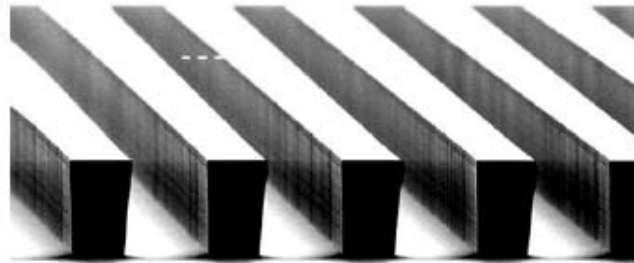
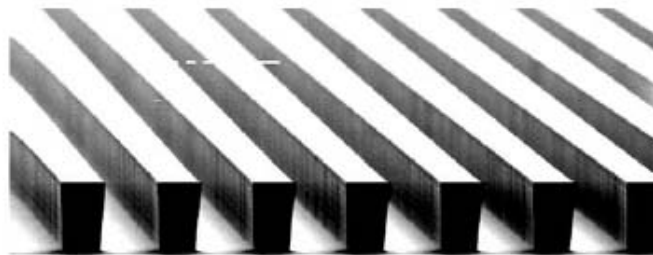
(c) Plasma Etching



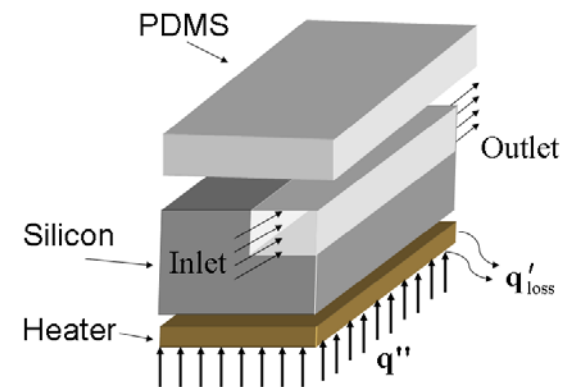
(e) Photo Resist Removal



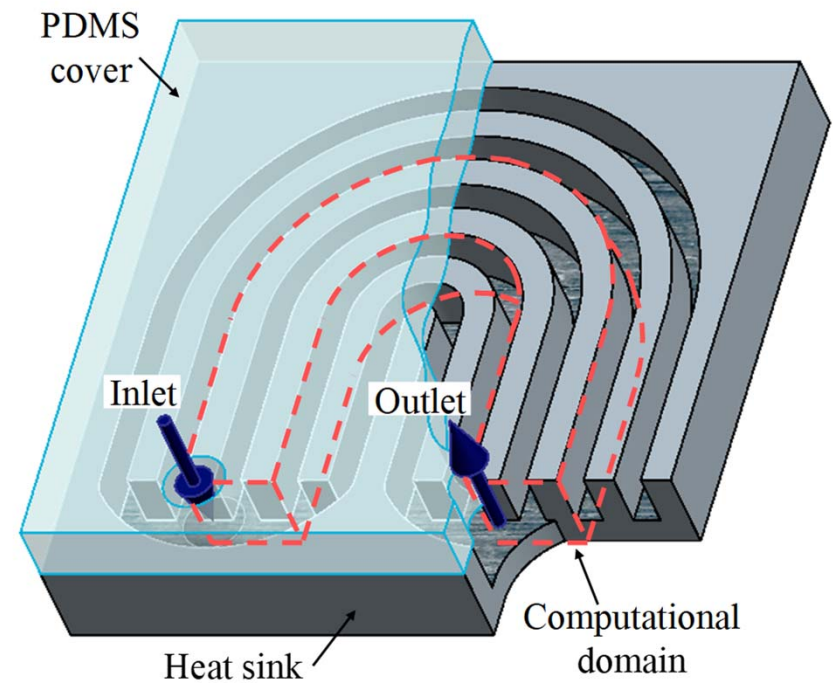
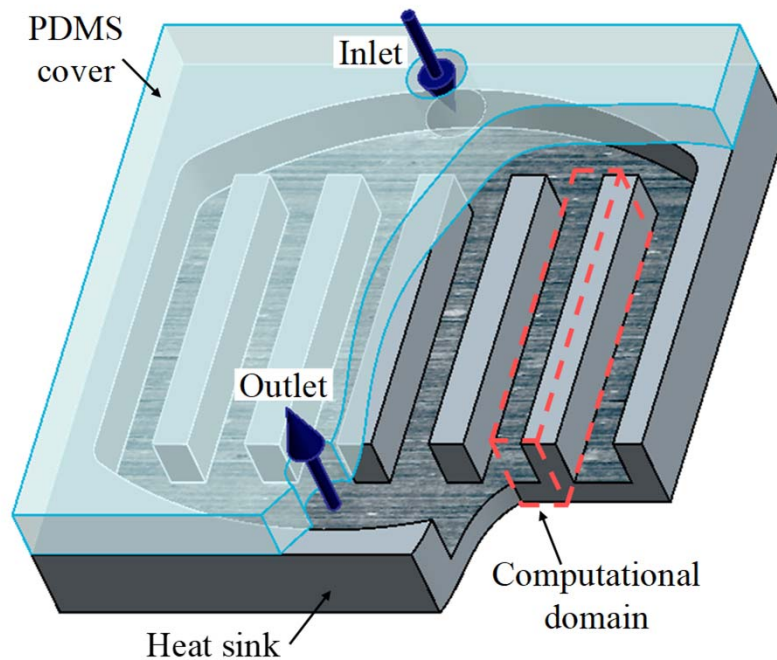
(f) PDMS/Silicon Bonding



Plasma
Etching



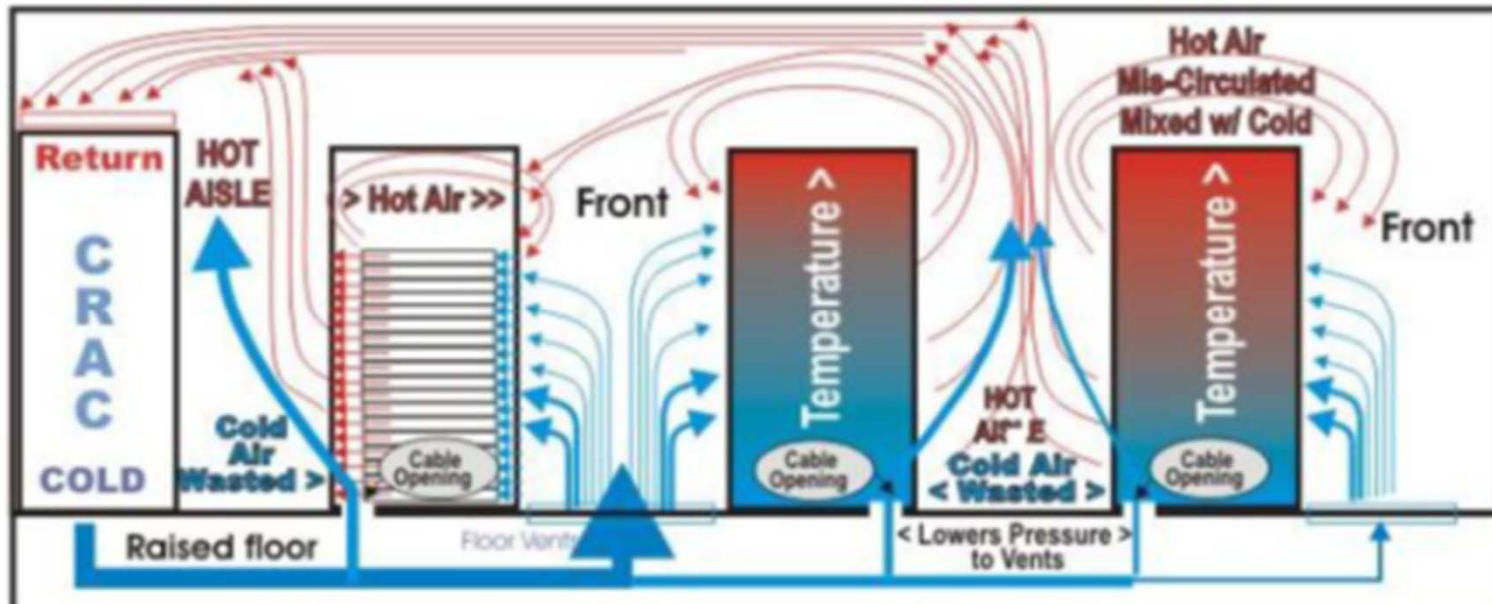
Schematic of Straight and U-Shaped Microchannels



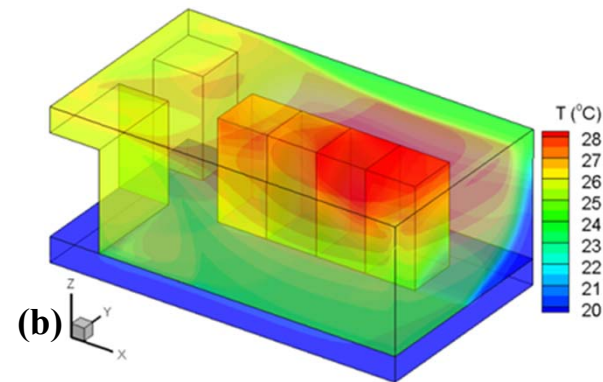
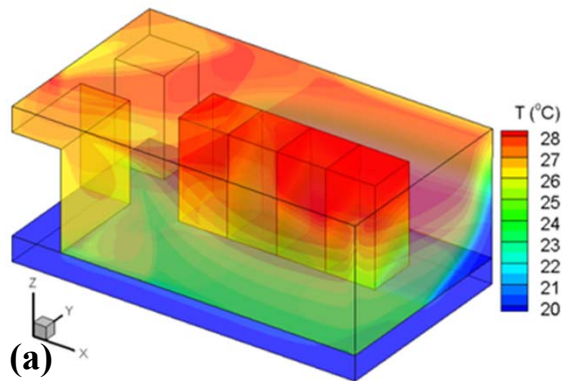
A Typical Data Center



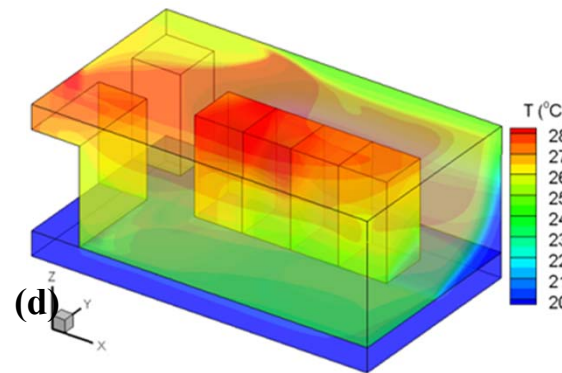
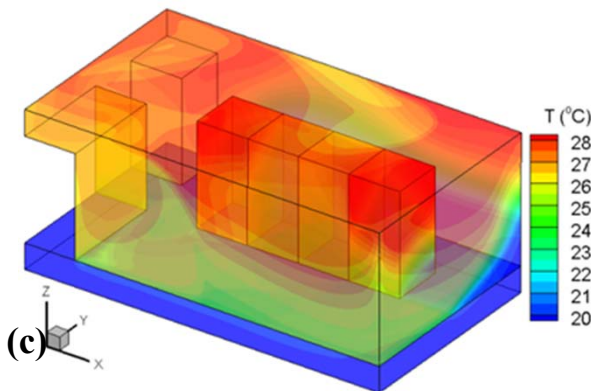
Three-Dimensional CFD Data Center Model



Temperature Distribution in the Data Center Room with 50% Utilization



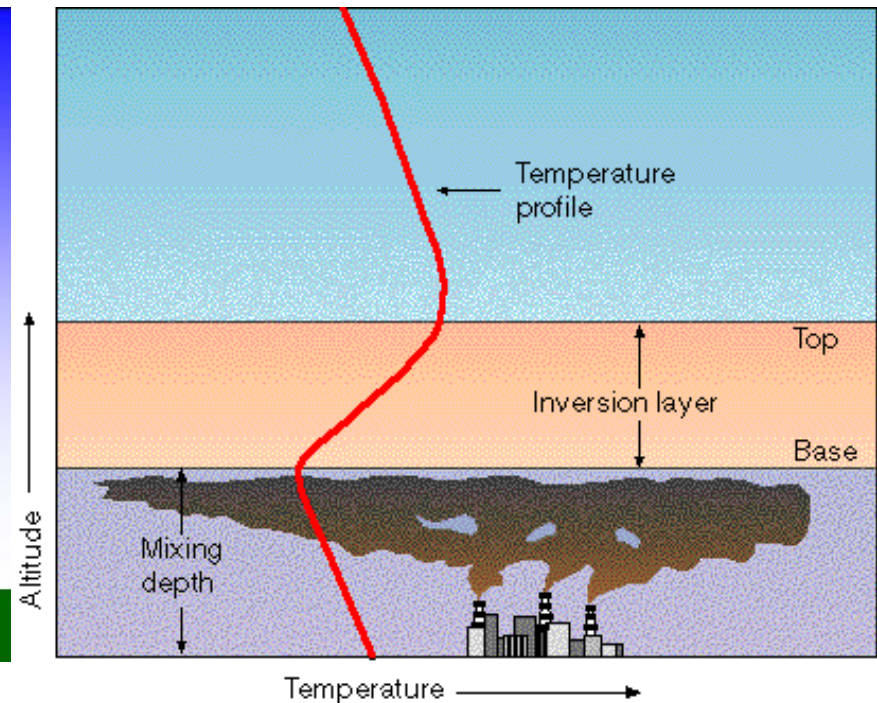
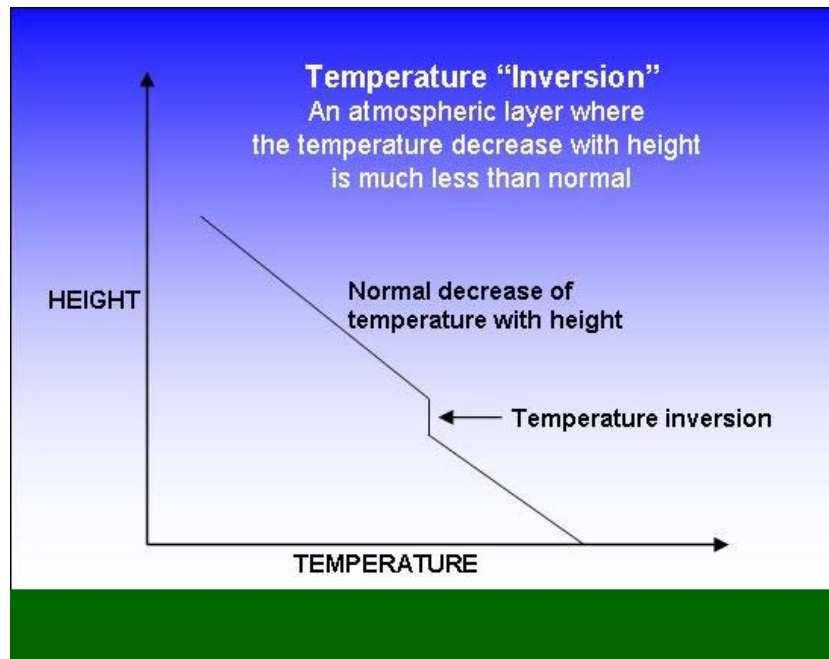
(a) A and C racks are operating, flow rate 4650CFM (b) A and C racks are operating, flow rate 5650
(c) A and D racks are operating, flow rate 4650CFM (d) A and B racks are operating, flow rate 4650CFM



Temperature Inversion



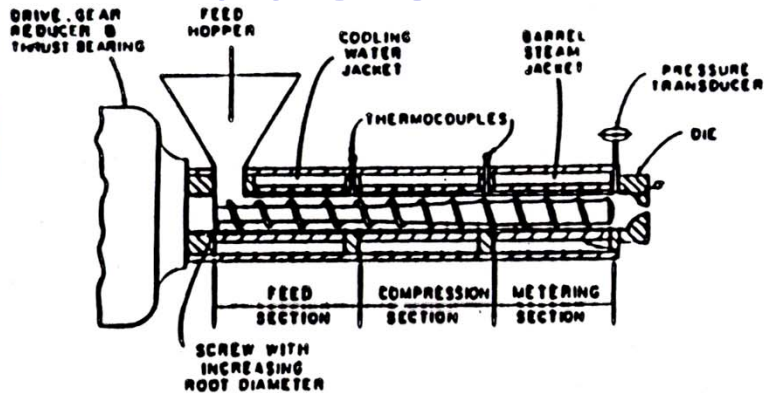
Temperature Inversion



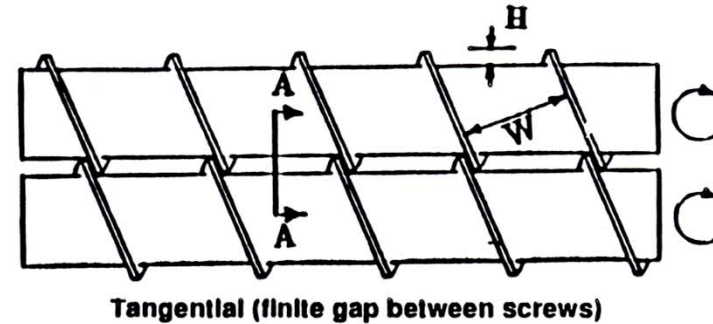
© 1998 Wadsworth Publishing Company/ITP

Single- and Twin-Screw Polymer Extruders

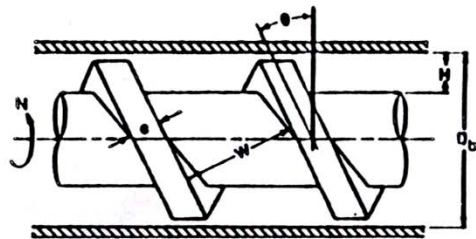
Schematic of a single screw extruder



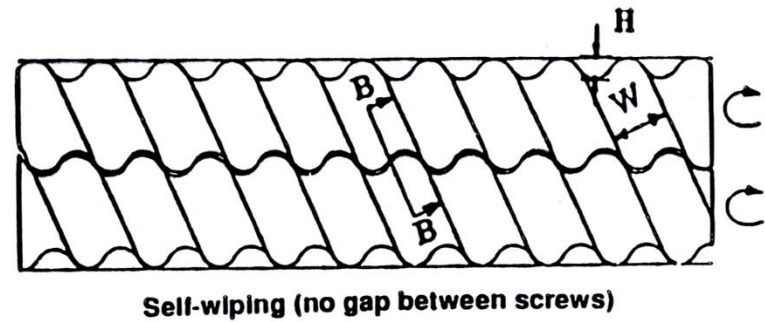
Schematic of twin-screw geometries



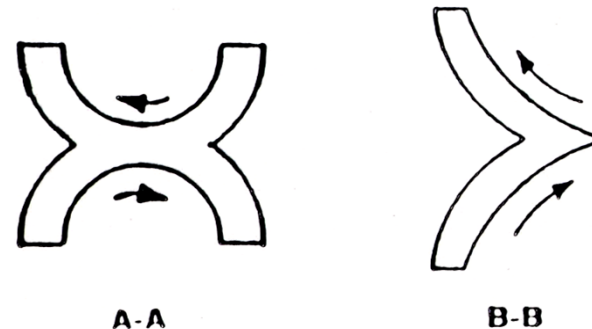
Schematic of a single screw with shallow rectangular channel



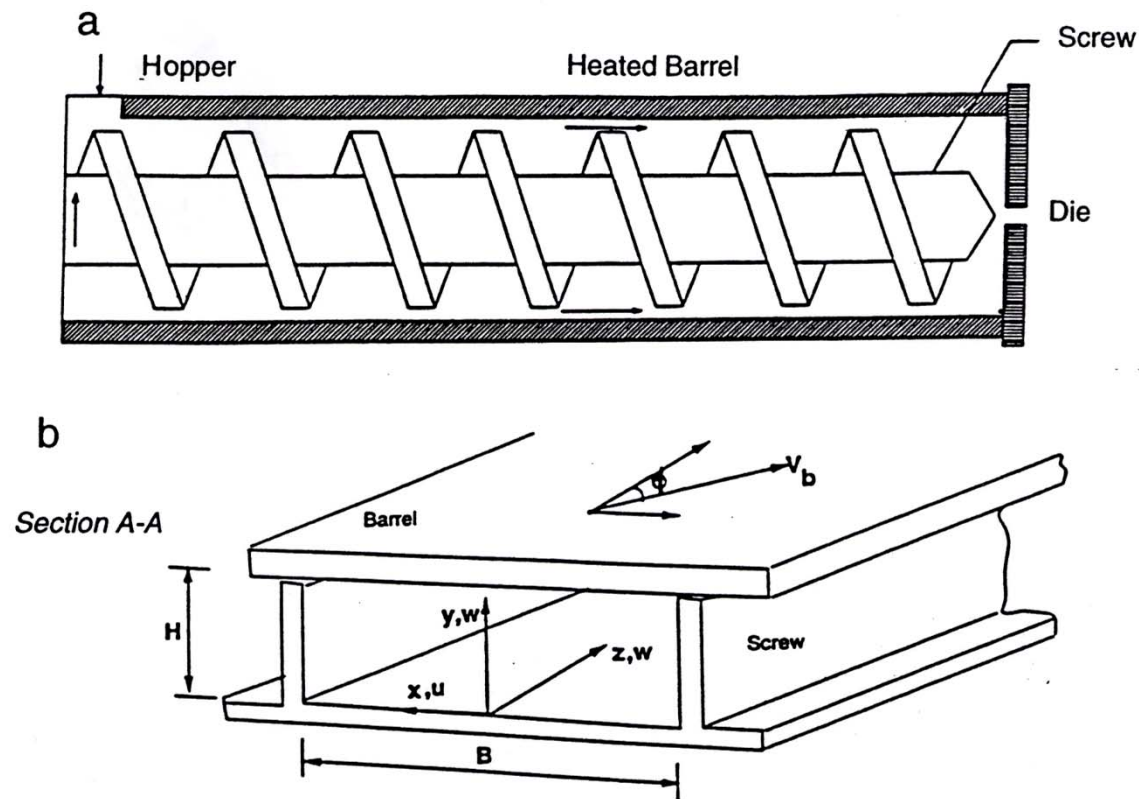
Schematic of a single screw with curved channel



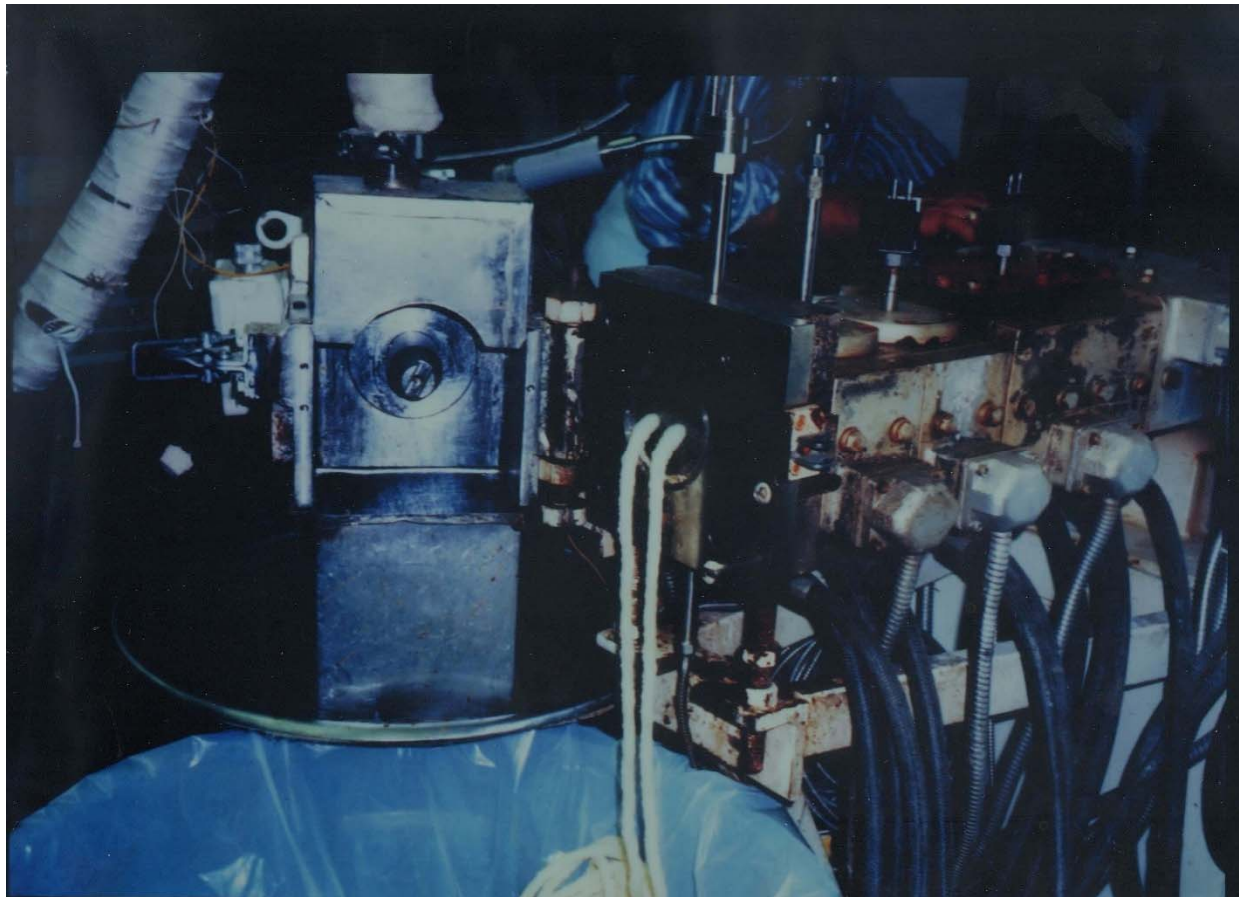
Cross Sections



Sketch of Single-Screw Polymer Extruder

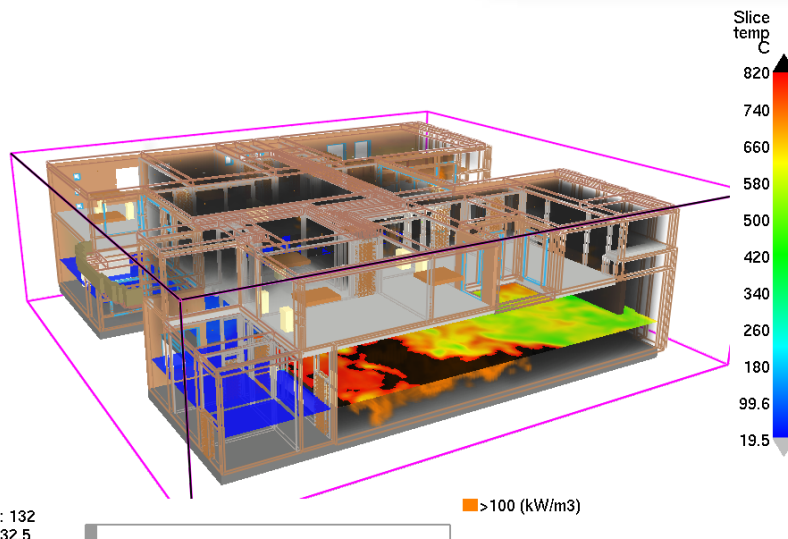


Twin-Screw Food Extruder

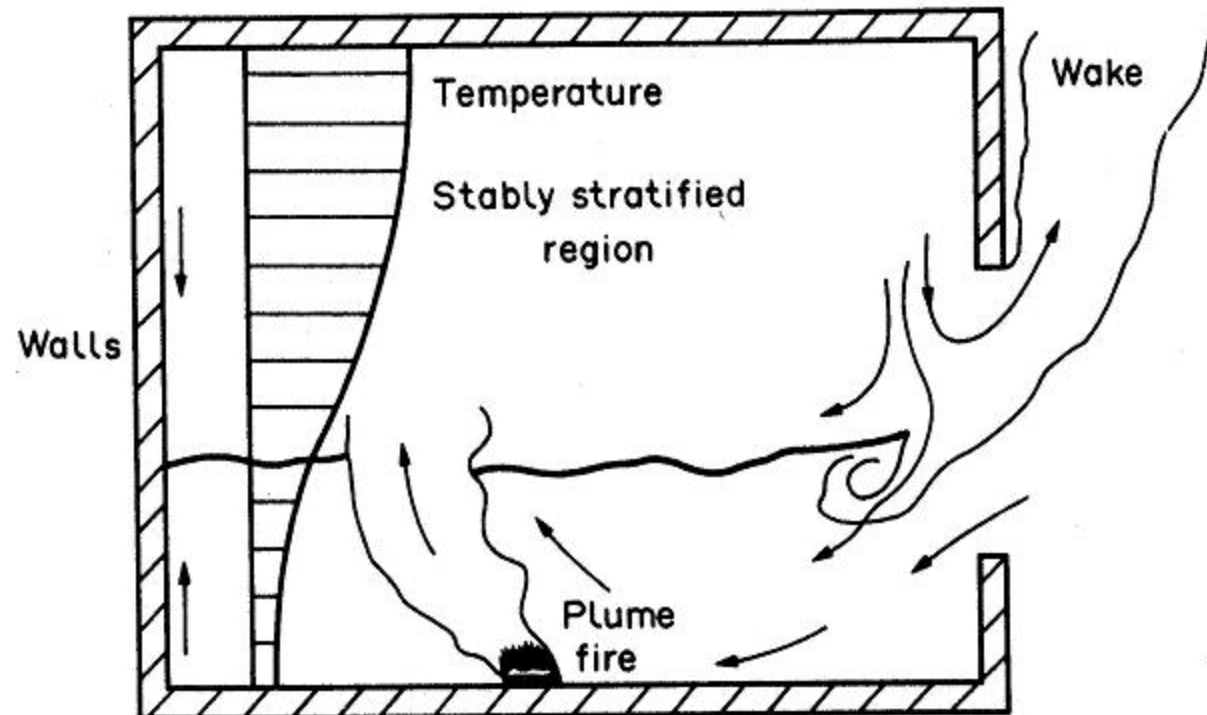


- Feed Hopper
- Rotating Screw
- Extruder Channel
- Heating/Cooling Arrangement
- Die

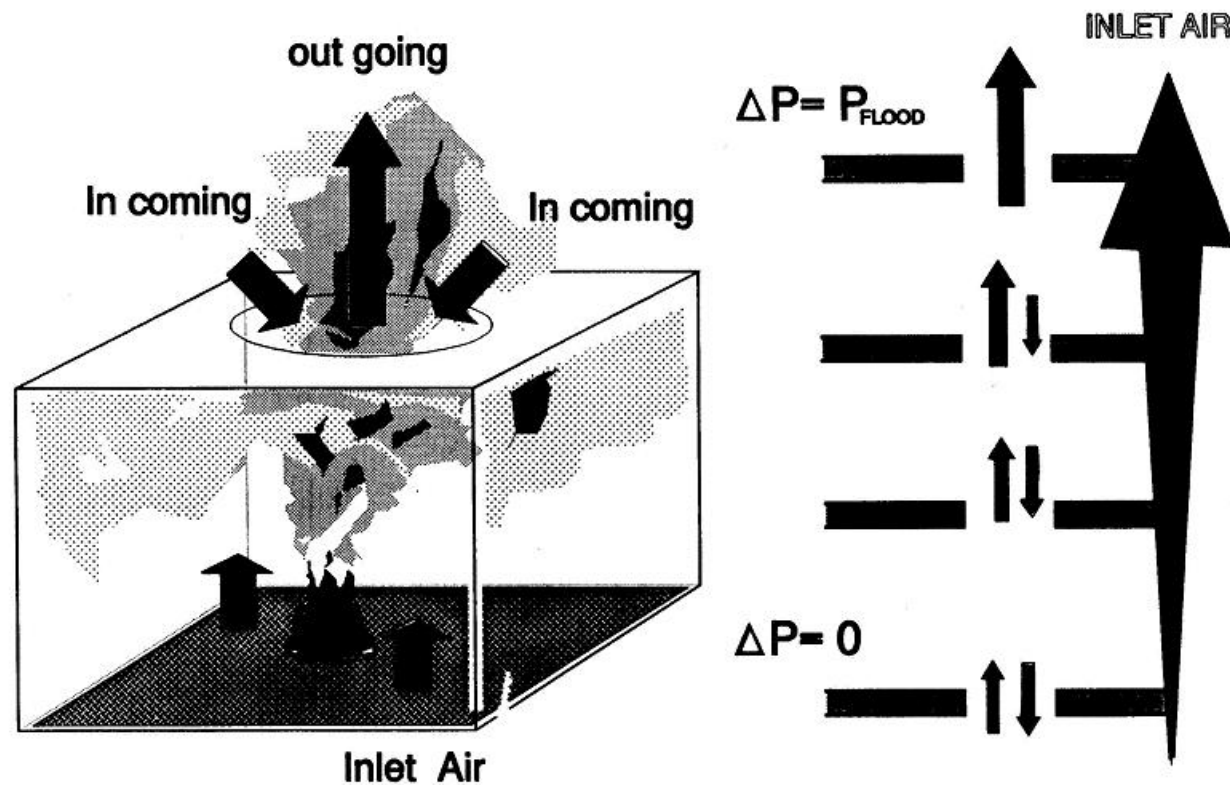
Safety Issues with Fires, Explosions and Other Accidents



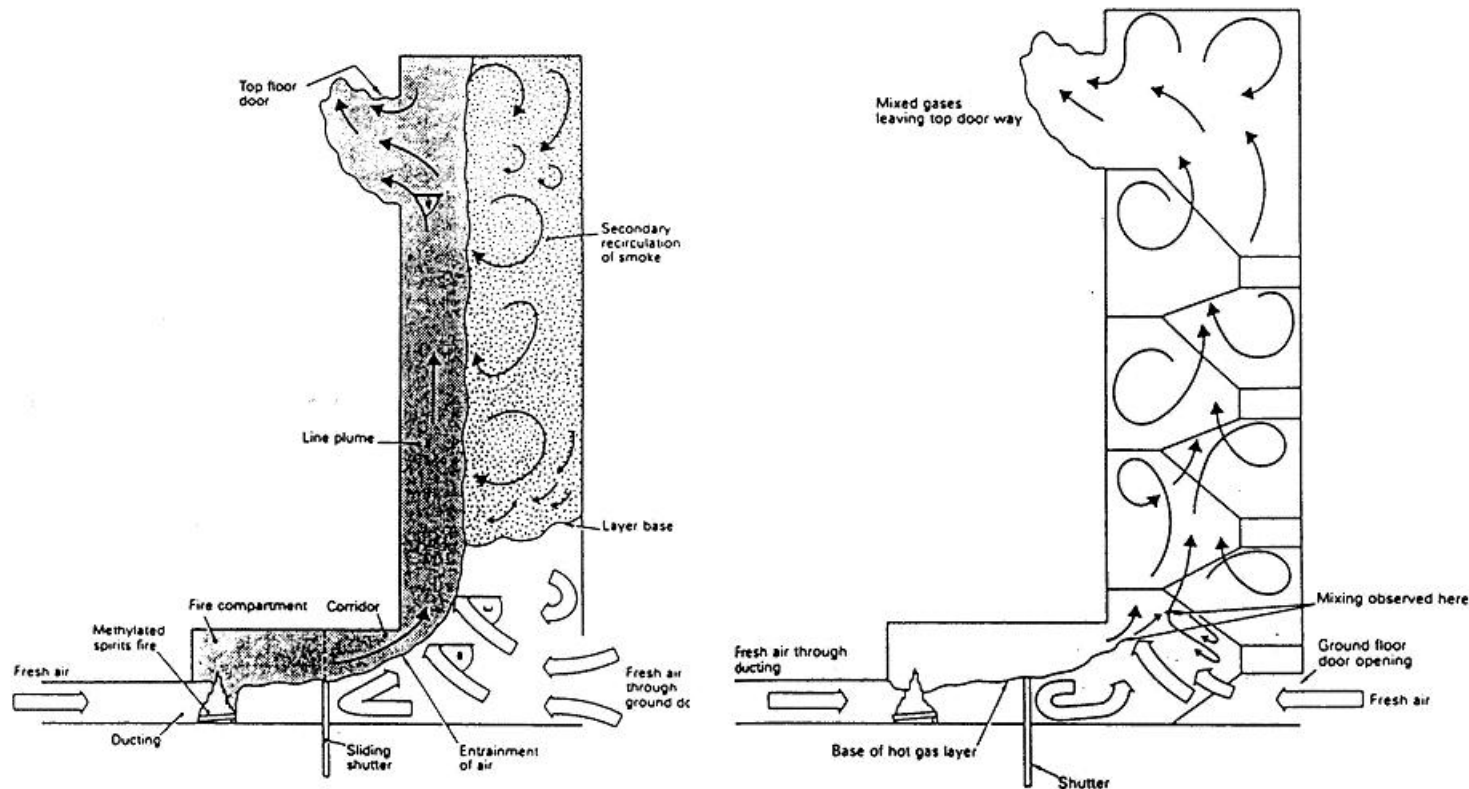
A Typical Room Fire



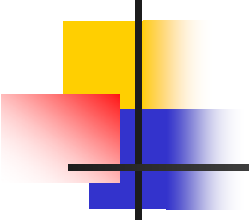
Flow in an Enclosure with a Single Horizontal Vent



Flows in a Vertical Elevator Shaft and in a Stairwell



From Marshall (1986)



The Optimization Problem

MAXIMIZE

- Efficiency/Effectiveness
- Heat transfer rate
- Product quality: Uniformity, purity
- Productivity: Rate of production, speed

MINIMIZE

- Energy and material losses
- Pressure drop
- Entropy generation
- Defects: Voids, impurities
- Costs: Capital, operating costs